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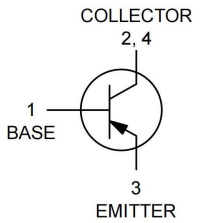
MJD5731T4G
High Voltage PNP Silicon Power Transistors

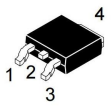
Designed for line operated audio output amplifier, SWITCHMODE power supply drivers and other switching applications.

Features

- PNP Complements to the MJD47 thru MJD50 Series
- Epoxy Meets UL 94 V−0 @ 0.125 in
- These Devices are Pb−Free and are RoHS Compliant

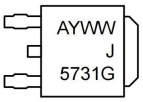
SILICON
POWER TRANSISTORS
1.0 AMPERE
350 VOLTS, 15 WATTS





DPAK
CASE 369C
STYLE 1

MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
J5731 = Device Code
G = Pb−Free Package

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector−Emitter Voltage	V_{CEO}	350	Vdc
Emitter−Base Voltage	V_{EB}	5	Vdc
Collector Current − Continuous	I_C	1.0	Adc
Collector Current − Peak	I_{CM}	3.0	Adc
Total Power Dissipation @ T_C = 25°C Derate above 25°C	P_D	 15 0.12	 W W/°C
Total Power Dissipation (Note 1) @ T_A = 25°C Derate above 25°C	P_D	 1.56 0.0125	 W W/°C
Unclamped Inductive Load Energy (See Figure 10)	E	20	mJ
Operating and Storage Junction Temperature Range	T_J, T_{stg}	−55 to +150	°C
ESD − Human Body Model	HBM	3B	V
ESD − Machine Model	MM	C	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. These ratings are applicable when surface mounted on the minimum pad sizes recommended.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction−to−Case	$R_{\theta JC}$	8.33	°C/W
Thermal Resistance, Junction−to−Ambient (Note 2)	$R_{\theta JA}$	80	°C/W
Lead Temperature for Soldering	T_L	260	°C

2. These ratings are applicable when surface mounted on the minimum pad sizes recommended.

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ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector−Emitter Sustaining Voltage (Note 3) (I_C = 30 mAdc, I_B = 0)	$V_{CEO(sus)}$	350	–	Vdc
Collector Cutoff Current (V_{CE} = 250 Vdc, I_B = 0)	I_{CEO}	–	0.1	mAdc
Collector Cutoff Current (V_{CE} = 350 Vdc, V_{BE} = 0)	I_{CES}	–	0.01	mAdc
Emitter Cutoff Current (V_{BE} = 5.0 Vdc, I_C = 0)	I_{EBO}	–	0.5	mAdc
ON CHARACTERISTICS (Note 3)				
DC Current Gain (I_C = 0.3 Adc, V_{CE} = 10 Vdc) (I_C = 1.0 Adc, V_{CE} = 10 Vdc)	h_{FE}	30 10	175 –	–
Collector−Emitter Saturation Voltage (I_C = 1.0 Adc, I_B = 0.2 Adc)	$V_{CE(sat)}$	–	1.0	Vdc
Base−Emitter On Voltage (I_C = 1.0 Adc, V_{CE} = 10 Vdc)	$V_{BE(on)}$	–	1.5	Vdc
DYNAMIC CHARACTERISTICS				
Current Gain − Bandwidth Product (I_C = 0.2 Adc, V_{CE} = 10 Vdc, f = 2.0 MHz)	f_T	10	–	MHz
Small−Signal Current Gain (I_C = 0.2 Adc, V_{CE} = 10 Vdc, f = 1.0 kHz)	h_{fe}	25	–	–

3. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

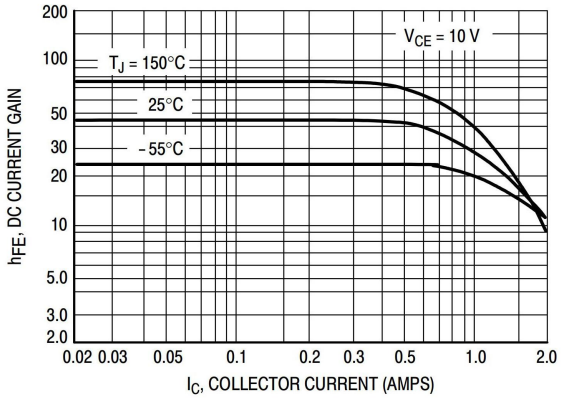

Figure 1. DC Current Gain

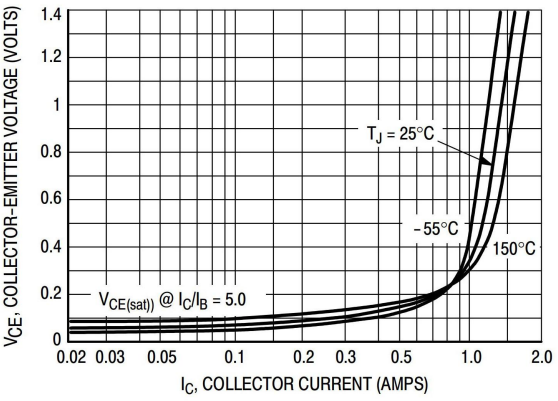

Figure 2. Collector−Emitter Saturation Voltage

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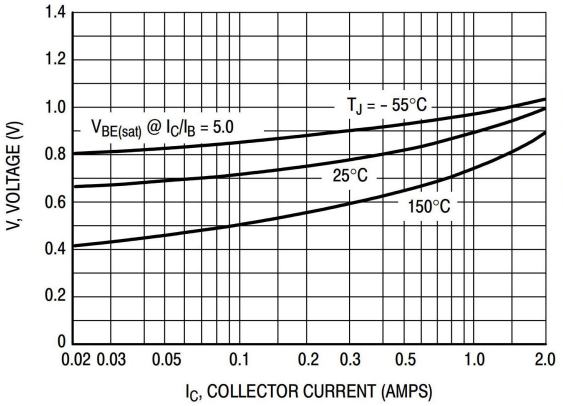

Figure 3. Base−Emitter Voltage

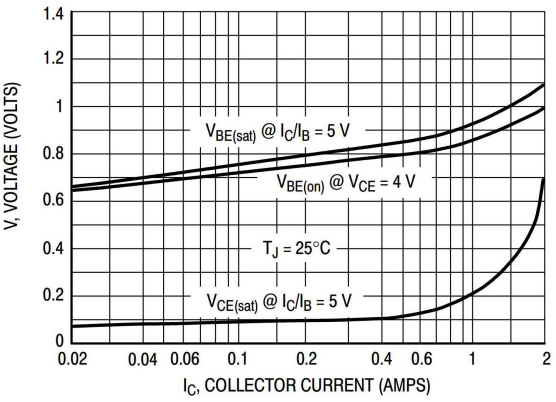

Figure 4. “On” Voltages

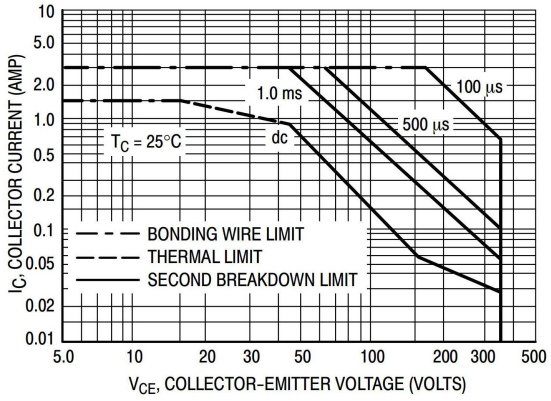

Figure 5. Forward Bias Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 5 is based on $T_{J(pk)}$ = 150°C; T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150°C$. $T_{J(pk)}$ may be calculated from the data in Figure 6. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

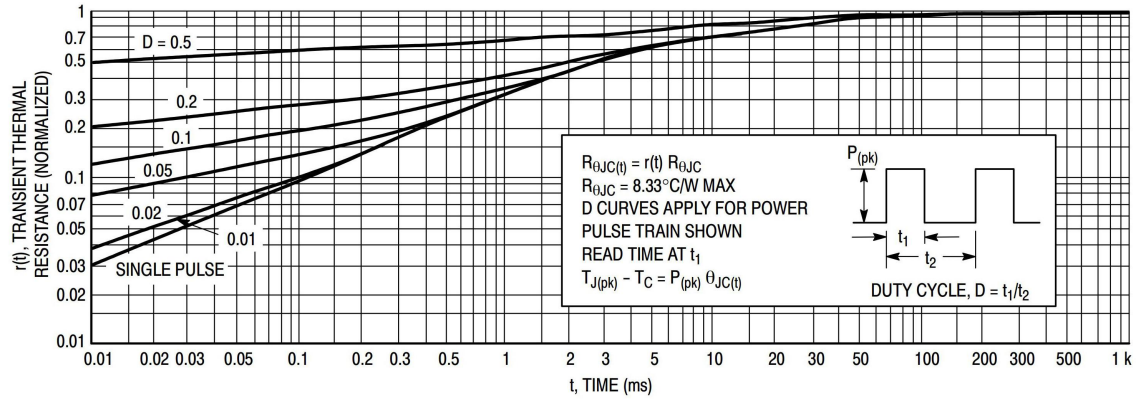

Figure 6. Thermal Response

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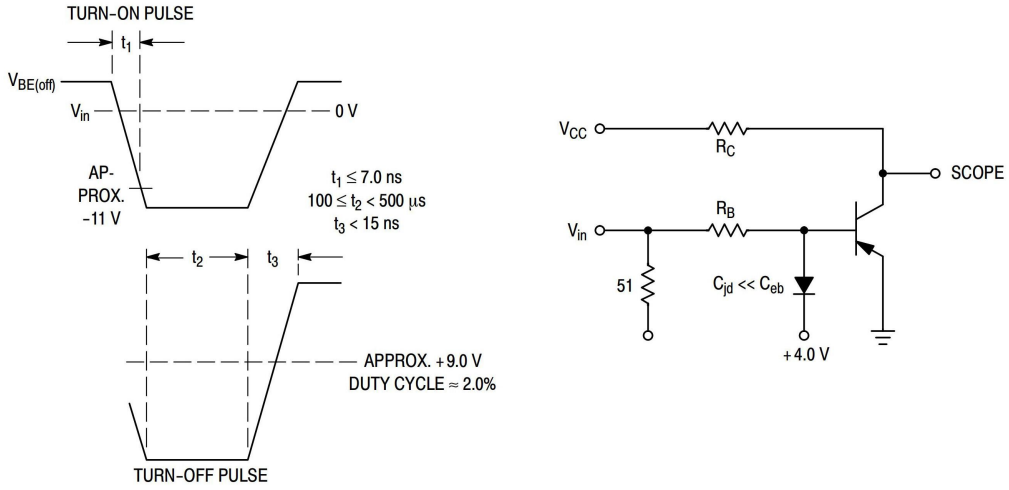


Figure 7. Switching Time Equivalent Circuit

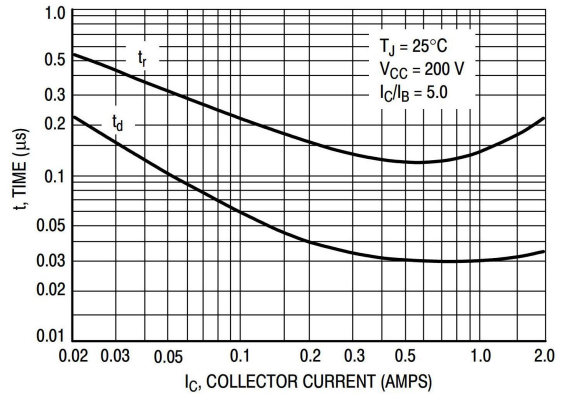


Figure 8. Turn−On Resistive Switching Times

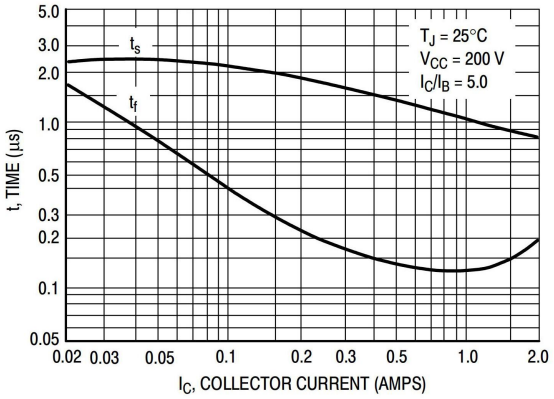
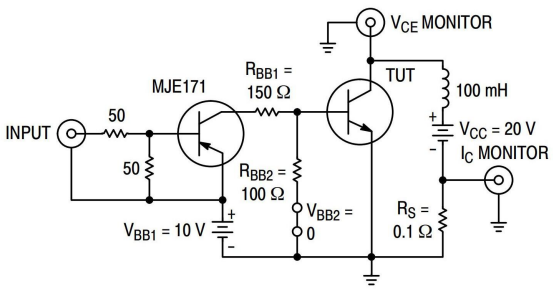


Figure 9. Resistive Turn−Off Switching Times

Test Circuit



Voltage and Current Waveforms

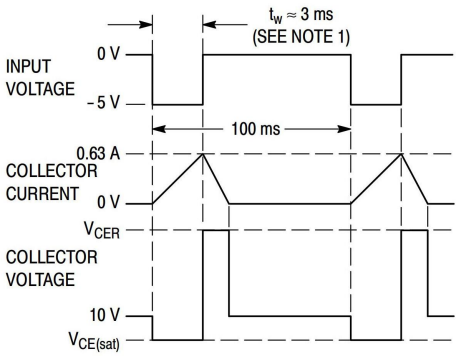


Figure 10. Inductive Load Switching

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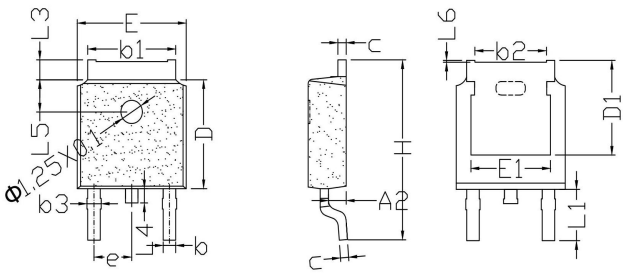
Ordering Information

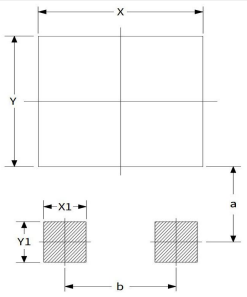
PACKAGE	PACKAGE CODE	UNIT WEIGHT(g)	REEL(pcs)	BOX(pcs)	CARTON(pcs)	DELIVERY MODE
TO-252	R3	0.305	2500	5000	25000	13''

Package Outline Dimensions (TO-252)



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A2	0.90	1.10	0.035	0.043
b	0.66	0.86	0.026	0.034
b1	5.10	5.46	0.201	0.215
b2	4.27	4.37	0.168	0.172
b3	0.78	0.90	0.031	0.035
c	0.45	0.55	0.018	0.022
D	5.90	6.30	0.232	0.248
D1	5.35 REF.		0.211REF.	
E	6.30	6.70	0.248	0.264
E1	4.83 REF.		0.190 REF.	
e	2.18	2.38	0.086	0.094
H	9.80	10.4	0.386	0.409
L1	2.70	3.10	0.106	0.122
L3	0.80	1.20	0.031	0.047
L4	0.60	1.00	0.024	0.039
L5	1.8 REF.		0.071 REF.	
L6	-	0.12	-	0.005

Suggested Pad Layout



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
a	3.70	-	0.146	-
b	4.37	-	0.172	-
X	-	5.80	-	0.228
X1	-	1.20	-	0.047
Y	-	5.85	-	0.230
Y1	-	2.00	-	0.079